UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LTD.,
Petitioner,

v.

MARLIN SEMICONDUCTOR LTD.,
Patent Owner.

Case IPR2026-00061
Patent No. 8,076,194

PETITIONER'S UPDATED EXHIBIT LIST

Pursuant to 37 C.F.R. § 42.63(e), Petitioner Taiwan Semiconductor Manufacturing Company Ltd. hereby submits a current listing of Petitioner's exhibits. Exhibits 1030-1051 are being filed today.

Exhibit	Description
1001	U.S. Patent No. 8,076,194 B2 to Tseng et al. ("'194 patent").
1002	Prosecution File History of the '194 patent.
1003	Declaration of Dr. Eugene Fitzgerald, Ph.D.
1004	Curriculum Vitae of Dr. Eugene Fitzgerald, Ph.D.
1005	U.S. Pat. No. 7,579,262 B2 to Hoentschel et al. ("Hoentschel262")
1006	U.S. Pat. No. 7,605,407 B2 to Wang ("Wang407").
1007	U.S. Pat. No. 7,449,753 B2 to Wang et. al. ("Wang753")
1008	S.M. Sze, *Physics of Semiconductor Devices.* (2d ed. 1981) (excerpted).
1009	J.D. Plummer et al., *Silicon VLSI Technology: Fundamentals, Practice and Modeling* (2000) (excerpted).
1010	D. James, "2004 – The Year of 90-nm: A Review of 90 nm Devices," 2005 IEEE/SEMI Advanced Semiconductor Manufacturing Conference, pp. 72-76 (2005).
1011	S.E. Thompson et al., "A 90-nm Logic Technology Featuring Strained-Silicon," IEEE Transactions on Electron Devices, vol. 51. No. 11, pp. 1790-97 (Nov. 2004).
1012	U.S. Pat. Pub. No. 2006/0148151 A1 to Murthy et al.
1013	U.S. Pat. Pub. No. 2004/0262683 A1 to Bohr et al.

Exhibit	Description
1014	T. Ghani et al., "A 90nm High Volume Manufacturing Logic Technology Featuring Novel 45nm Gate Length Strained Silicon CMOS Transistors," Technical Digest of the 2003 IEEE International Electron Devices Meeting ("IEDM"), pp. 978-80 (Dec. 10, 2003).
1015	U.S. Pat. Pub. No. 2007/0034906 A1 to Wang et al. ("Wang906").
1016	U.S. Pat. Pub. No. 2006/0286729 A1 to Kavalieros et al.
1017	P. Bai et al., "A 65nm Logic Technology Featuring 35nm Gate Lengths, Enhanced Channel Strain, 8 Cu Interconnect Layers, Low-k ILD and 0.57 μm^2 SRAM Cell," Technical Digest of the 2004 IEEE International Electron Devices Meeting (IEDM), pp. 657-60 (Dec. 2004).
1018	Excerpts from C.Y. Chang & S.M Sze, *ULSI Technology* (1996).
1019	Excerpts from S. Wolf, *Silicon Processing for the VLSI Era, Volume 2: Process Integration* (1990).
1020	G.E. Moore, *Lithography and the Future of Moore's Law*, Proceedings of the Society of Photo-Optical Instrumentation Engineers (SPIE) 2437, pp. 2-17 (May 19, 1995).
1021	Excerpts from S. Wolf, *Silicon Processing for the VLSI Era, Volume 3: The Submicron MOSFET* (1995).
1022	M. Quirk & J. Serda, *Semiconductor Manufacturing Technology* (2001) (excerpted).
1023	A. Wei T. Kammler, J. Höntschel & M. Horstmann, et al., "Combining Embedded and Overlayer Compressive Stressors in Advanced SOI CMOS Technologies," Extended Abstracts of the 2005 International Conference on Solid State Devices and Materials ("SSDM"), pp. 32-33 (Sept. 2005).

Exhibit	Description
1024	M. Horstmann, A. Wei T. Kammler & J. Höntschel, et al., "Integration and Optimization of Embedded-SiGe, Compressive and Tensile Stressed Liner Films, and Stress Memorization in Advanced SOI CMOS Technologies," 2005 IEEE International Electron Devices Meeting ("IEDM"), pp. 1-4 (Dec. 2005).
1025	U.S. Patent No. 6,043,545 to Tseng et al.
1026	U.S. Patent No. 6,391,732 to Gupta et al.
1027	J. Damiano et al., "Characterization and Elimination of Trench Dislocations," Digest of Technical Papers, 1998 Symposium on VLSI Technology, pp. 212-13 (June 1998).
1028	U.S. Patent Appl. Pub. No. 2005/0040479 to Koldiaev et al.
1029	U.S. Patent No. 6,191,462 to Chen-Hua.
1030	U.S. Patent No. 6,815,770 to Chien et al. ("Chien770")
1031	Patent Assignment Abstract of Title for the '194 patent.
1032	Taiwan Semiconductor Manufacturing Company Ltd., 7nm Technology (last visited Aug. 13, 2025), *available at* https://www.tsmc.com/english/dedicatedFoundry/technology/logic/l_7nm
1033	Docket Navigator Search for United Microelectronics Corporation, conducted February 24, 2026.
1034	Jeremy Bowman, Nasdaq, This 1 Number May Ensure TSMC's Market Dominance, The Motley Fool (Aug. 17, 2024) (last visited July 18, 2025), available at https://www.nasdaq.com/articles/1-number-may-ensure-tsmcs-market-dominance.

Exhibit	Description
1035	"Another Historic Investment Secured Under President Trump," The White House, Published Mar. 3, 2025 https://www.whitehouse.gov/articles/2025/03/another-historic-investment-secured-under-president-trump/ (last accessed Feb. 25, 2026)
1036	"IPValue Affiliate Licenses Samsung to Marlin Semiconductor Patent Portfolio," IPValue https://ipvalue.com/news/ipvalue-affiliate-licenses-samsung-to-marlin-semic (last accessed Feb. 25, 2026)
1037	"IPValue Affiliate Licenses Samsung to Marlin Semiconductor Patent Portfolio," Businesswire, Published May 22, 2025 https://www.businesswire.com/news/home/20250504309443/en/IPValue-Affiliate-Licenses-Samsung-to-Marlin-Semiconductor-Patent-Portfolio (last accessed Feb. 25, 2026)
1038	U.S. Patent No. 8,63,070 to Fung et al. ("'070 patent")
1039	"CNBC Transcript: United States Commerce Secretary Howard Lutnick Speaks with CNBC's Brian Sullivan on 'The Exchange' Today," CNBC, Published Apr. 29, 2025 https://www.cnbc.com/2025/04/29/cnbc-transcript-united-states-commerce-secretary-howard-lutnick-speaks-with-cnbcs-brian-sullivan-on-the-exchange-today.html (last accessed Feb. 25, 2026)

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1040	"Removing Barriers to American Leadership in Artificial Intelligence," The White House, Published Jan. 23, 2025 https://www.whitehouse.gov/presidential-actions/2025/01/removing-barriers-to-american-leadership-in-artificial-intelligence/ (last accessed Feb. 25, 2026)
1041	TSMC Annual Report 2024 (Excerpts) https://investor.tsmc.com/static/annualReports/2024/english/ebook/index.html (last accessed Feb. 25, 2026)
1042	"Ansys Strengthens Collaboration with TSMC on Advanced Node Processes Certification and 3D-IC Multiphysics Design Solutions.," Published Apr. 23, 2025 https://investors.ansys.com/news-releases/news-release-details/ansys-strengthens-collaboration-tsmc-advanced-node-processes (last accessed Feb. 25, 2026)
1043	TSMC-Cadence Press Release, Published Apr. 24, 2025 https://www.cadence.com/en_US/home/company/newsroom/press-releases/pr/2025/cadence-and-tsmc-advance-ai-and-3d-ic-chip-design-with-certified.html (last accessed Feb. 25, 2026)
1044	"TSMC's Resurgence: What Lies Ahead for the Architect of AI," Published June 11, 2025 https://www.cmcmarkets.com/en-au/market-news/tsmc-resurgence (last accessed Feb. 25, 2026)

Exhibit	Description
1045	J. Klearman, "Decoding TSMC's Contribution to the AI and 5G Ecosystem," Nov. 20, 2024 https://graniteshares.com/institutional/us/en-us/research/decoding-tsmc-s-contribution-to-the-ai-and-5g-ecosystem/ (last accessed Feb. 25, 2026)
1046	A. Shilov, "Both Trump and Biden expected to attend TSMC's Arizona fab grand opening ceremony – Fab 21 opens in December," Yahoo! Finance – tom'sHardware, Published Nov. 8, 2024 https://finance.yahoo.com/news/both-trump-biden-expected-attend-151941592.html (last accessed Feb. 25, 2026)
1047	R. O'Brien, "Trump on China – Putting America First," https://trumpwhitehouse.archives.gov/wp-content/uploads/2020/11/Trump-on-China-Putting-America-First.pdf (last accessed Feb. 25, 2026)
1048	K. Zhai, The changing landscape of semiconductor manufacturing: why the health sector should care. NIH National Library of Medicine, Published June 12, 2023 https://pmc.ncbi.nlm.nih.gov/articles/PMC10292744/ (last accessed Feb. 25, 2026)
1049	*Certain Foreign-Fabricated Semiconductor Devices, Products Containing the Same, and Components Thereof*, Inv. No. 337-TA-1443, Doc ID 2324200 (Feb. 18, 2025) (Complaint Public Exhibit 18)

Exhibit	Description
1050	*Certain Foreign-Fabricated Semiconductor Devices, Products Containing the Same, and Components Thereof*, Inv. No. 337-TA-1443, Doc ID 844949 (Mar. 4, 2025) (TSMC's 100-Day Request)
1051	*Certain Foreign-Fabricated Semiconductor Devices, Products Containing the Same, and Components Thereof*, Inv. No. 337-TA-1443, Doc ID 843707 (Feb. 18, 2025) (Complaint)

Respectfully submitted,

Dated: March 12, 2026

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CERTIFICATE OF SERVICE

The undersigned hereby certifies that a copy of the foregoing **Petitioner's Updated Exhibit List** and **Exhibits 1030-1051** were served on March 12, 2026, via e-mail directed to counsel of record for the Patent Owner at the following:

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